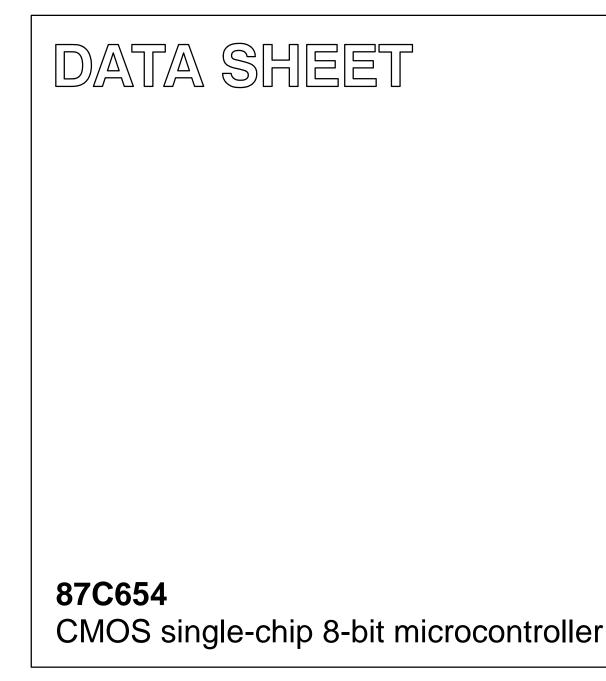
INTEGRATED CIRCUITS



Product specification IC20 Data Handbook 1996 Aug 16



Philips Semiconductors



87C654

DESCRIPTION

The 87C654 Single-Chip 8-Bit Microcontroller is manufactured in an advanced CMOS process and is a derivative of the 80C51 microcontroller family. The 87C654 has the same instruction set as the 80C51. Two versions of the derivative exist:

83C654—16k bytes mask programmable ROM

87C654—EPROM version

This device provides architectural enhancements that make it applicable in a variety of applications for general control systems. The 87C654 contains a non-volatile $16k \times 8$ EPROM, a volatile 256×8 read/write data memory, four 8-bit I/O ports, two 16-bit timer/event counters (identical to the timers of the 80C51), a multi-source, two-priority-level, nested interrupt structure, an I²C interface, UART and on-chip oscillator and timing circuits. For systems that require extra capability, the 87C654 can be expanded using standard TTL compatible memories and logic.

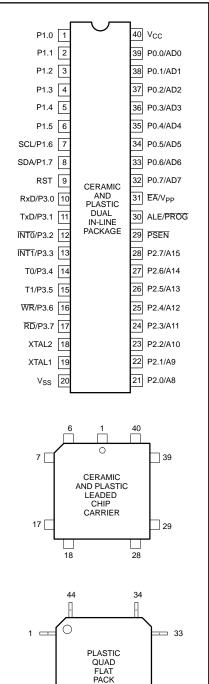
The device also functions as an arithmetic processor having facilities for both binary and BCD arithmetic plus bit-handling capabilities. The instruction set consists of over 100 instructions: 49 one-byte, 45 two-byte and 17 three-byte. With a 16MHz crystal, 58% of the instructions are executed in 0.75 μ s and 40% in 1.5 μ s. Multiply and divide instructions require 3 μ s.



FEATURES

- 80C51 central processing unit
- 16k × 8 EPROM expandable externally to 64k bytes
- 256 × 8 RAM, expandable externally to 64k bytes
- Two standard 16-bit timer/counters
- Four 8-bit I/O ports
- I²C-bus serial I/O port with byte oriented master and slave functions
- Full-duplex UART facilities
- Power control modes
 - Idle mode
- Power-down mode
- Five package styles
- Extended temperature range
- OTP package available
- Two speed ranges
- 16MHz
- 20MHz

PIN CONFIGURATIONS



11

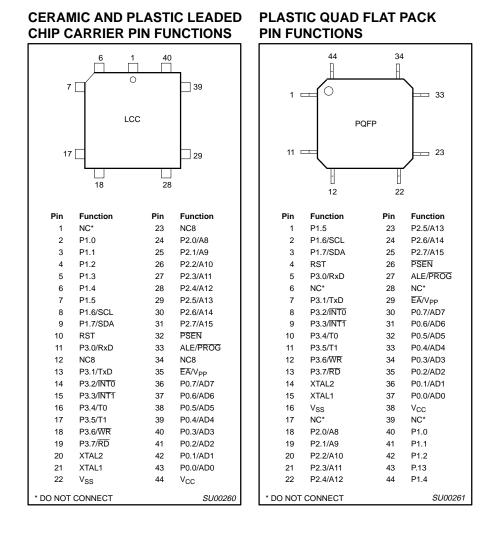
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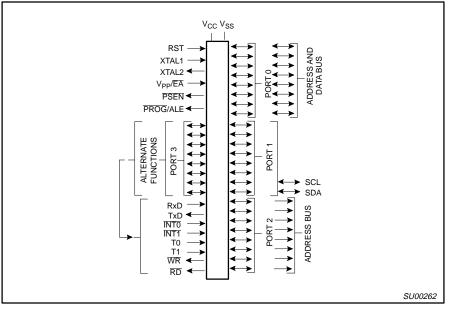
SU00259

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87C654



LOGIC SYMBOL



1996 Aug 16

CMOS single-chip 8-bit microcontroller

ORDERING INFORMATION

ORDEF	PS PART R NUMBER MARKING		TH AMERICA R NUMBER		TEMPERATURE RANGE °C	
ROMIess	ROM	ROMIess	ROM	Drawing Number	AND PACKAGE	FREQ MHz
P80C652FBP	P83C654FBP/xxx	S80C652FBPN	S83C654FBPN	SOT129-1	0 to +70, Plastic Dual In-line Package	16
					0 to +70, Ceramic Dual In-line Package w/Window	16
P80C652FBA	P83C654FBA/xxx	S80C652FBAA	S83C654FBAA	SOT187-2	0 to +70, Plastic Leaded Chip Carrier	16
P80C652FBB	P83C654FBB/xxx	S80C652FBBB	S83C654FBBB	SOT307-2 ⁴	0 to +70, Plastic Quad Flat Pack	16
P80C652FFP	P83C654FFP/xxx	S80C652FFPN	S83C654FFPN	SOT129-1	-40 to +85, Plastic Dual In-line Package	16
P80C652FFA	P83C654FFA/xxx	S80C652FFAA	S83C654FFAA	SOT187-2	-40 to +85, Plastic Leaded Chip Carrier	16
P80C652FFB	P83C654FFB/xxx	S80C652FFBB	S83C654FFBB	SOT307-2 ⁴	-40 to +85, Plastic Quad Flat Pack	16
P80C652FHP	P83C654FHP/xxx	S80C652FHPN	S83C654FHPN	SOT129-1	-40 to +125, Plastic Dual In-line Package	16
P80C652FHA	P83C654FHA/xxx	S80C652FHAA	S83C654FHAA	SOT187-2	-40 to +125, Plastic Leaded Chip Carrier	16
P80C652FHB	P83C654FHB/xxx	S80C652FHBB	S83C654FHBB	SOT307-2 ⁴	-40 to +125, Plastic Quad Flat Pack	16
DOUCEFOIDD		SOCCEDED		SOT120 4	0 to 170 Plantia Dual In line Dealersa	04
P80C652IBP P80C652IBA	P83C654IBP/xxx P83C654IBA/xxx	S80C652IBPN S80C652IBAA	S83C654IBPN S83C654IBAA	SOT129-1 SOT187-2	0 to +70, Plastic Dual In-line Package 0 to +70, Plastic Leaded Chip Carrier	24 24
P80C652IBA	P83C654IBB/xxx	S80C652IBAA S80C652IBBB	S83C654IBBB	SOT 307-2 ⁴	0 to +70, Plastic Leaded Chip Carrier	24
P80C652IFP	P83C654IFP/xxx	S80C652IBBB	S83C654IFPN	SOT307-21 SOT129-1	-40 to +85. Plastic Dual In-line Package	24
P80C652IFA	P83C654IFA/xxx	S80C652IFFN	S83C654IFAA	SOT129-1 SOT187-2	-40 to +85, Plastic Leaded Chip Carrier	24
P80C652IFA	P83C654IFB/xxx	S80C652IFAA	S83C654IFBB	SOT 307-2 ⁴	-40 to +85, Plastic Quad Flat Pack	24

Product specification

87C654

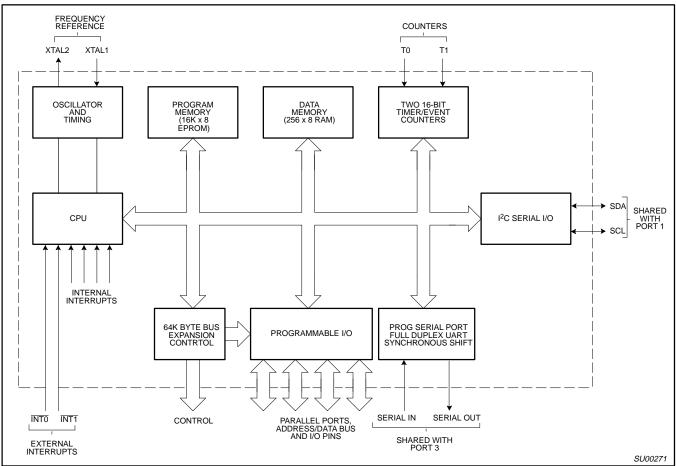
NOTES:

For full specification, see the 87C652 data sheet.
 87C654 frequency range is 3.5MHz – 16MHz or 3.5MHz – 24MHz.
 xxx denotes the ROM code number.
 SOT311 replaced by SOT307-2.

		TEMPERATURE RANGE °C	
EPROM	Drawing Number	AND PACKAGE	FREQ MHz
S87C654-4N40	SOT129-1	0 to +70, Plastic Dual In-line Package	16
S87C654-4F40	0590B	0 to +70, Ceramic Dual In-line Package w/Window	16
S87C654-4A44	SOT187-2	0 to +70, Plastic Leaded Chip Carrier	16
S87C654-4K44	1472A	0 to +70, Ceramic Leaded Chip Carrier w/Window	16
S87C654-4B44	SOT307-2	0 to +70, Plastic Quad Flat Pack	16
S87C654-5N40	SOT129-1	-40 to +85, Plastic Dual In-line Package	16
S87C654-5F40	0590B	-40 to +85, Ceramic Dual In-line Package w/Window	16
S87C654-5A44	SOT187-2	-40 to +85, Plastic Leaded Chip Carrier	16
S87C654-5B44	SOT307-2	-40 to +85, Plastic Quad Flat Pack	16
S87C654-7N40	SOT129-1	0 to +70, Plastic Dual In-line Package	20
S87C654–7F40	0590B	0 to +70, Ceramic Dual In-line Package w/Window	20
S87C654-7A44	SOT187-2	0 to +70, Plastic Leaded Chip Carrier	20
S87C654–7K44	1472A	0 to +70, Ceramic Leaded Chip Carrier w/Window	20
S87C654-8N40	SOT129-1	-40 to +85, Plastic Dual In-line Package	20
S87C654-8F40	0590B	-40 to +85, Ceramic Dual In-line Package w/Window	20
S87C654-8A44	SOT187-2	-40 to +85, Plastic Leaded Chip Carrier	20



Product specification



BLOCK DIAGRAM

PIN DESCRIPTIONS

	PI	N NUMB	ER		
MNEMONIC	DIP	LCC	QFP	TYPE	NAME AND FUNCTION
V _{SS}	20	22	16	Ι	Ground: 0V reference.
V _{CC}	40	44	38	I	Power Supply: This is the power supply voltage for normal, idle, and power-down operation.
P0.0–0.7	39–32	43–36	37–30	I/O	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s. Port 0 also outputs the code bytes during program verification in the 87C654. External pull-ups are required during program verification.
P1.0–P1.7	1–8	2–9	40–44, 1–3	I/O	Port 1 : Port 1 is an 8-bit bidirectional I/O port with internal pull-ups, except P1.6 and P1.7 which are open drain. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 1 also receives the low-order address byte during program memory verification. Alternate functions include:
P1.6 P1.7	7 8	8 9	2 3	I/O I/O	SCL: I ² C-bus serial port clock line. SDA: I ² C-bus serial port data line.
P2.0-P2.7	21–28	24–31	18–25	I/O	Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register.
P3.0–P3.7	10–17	11, 13–19	5, 7–13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 3 also serves the special features of the 80C51 family, as listed below:
	10 11 12 13 14 15 16 17	11 13 14 15 16 17 18 19	5 7 9 10 11 12 13	 0 0	RxD (P3.0): Serial input port TxD (P3.1): Serial output port INTO (P3.2): External interrupt INTT (P3.3): External interrupt T0 (P3.4): Timer 0 external input T1 (P3.5): Timer 1 external input WR (P3.6): External data memory write strobe RD (P3.7): External data memory read strobe
RST	9	10	4	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC} .
ALE/PROG	30	33	27	I/O	Address Latch Enable/Program Pulse: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input (PROG) during EPROM programming.
PSEN	29	32	26	0	Program Store Enable: The read strobe to external program memory. When the 87C654 is executing code from the external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.
EA/V _{PP}	31	35	29	I	External Access Enable/Programming Supply Voltage: EA must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH. If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH. This pin also receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming.
XTAL1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier.

NOTE:

To avoid "latch-up" effect at power-on, the voltage on any pin at any time must not be higher than V_{CC} + 0.5V or V_{SS} – 0.5V, respectively.

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BI MSB		SS, SYME	BOL, OR A	LTERNAT	IVE PORT	FUNCTIO	DN LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
В*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPTR:	Data pointer (2 bytes)										
DPH DPL	Data pointer high Data pointer low	83H 82H									00H 00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*#	Interrupt enable	A8H	EA		ES1	ES0	ET1	EX1	ET0	EX0	0x000000B
			BF	BE	BD	BC	BB	BA	B9	B8	
IP*#	Interrupt priority	B8H	-		PS1	PS0	PT1	PX1	PT0	PX0	xx000000B
			87	86	85	84	83	82	81	80	
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	FFH
			97	96	95	94	93	92	91	90	1
P1*#	Port 1	90H	SDA	SCL							FFH
			A7	A6	A5	A4	A3	A2	A1	A0	
P2*	Port 2	AOH	A15	A14	A13	A12	A11	A10	A9	A8	FFH
			B7	B6	B5	B4	B3	B2	B1	B0	
P3*	Port 3	B0H	RD	WR	T1	T0	INT1	INTO	TXD	RXD	FFH
PCON#	Power control	87H	SMOD	-	_	-	GF1	GF0	PD	IDL	0xxx0000B
			9F	9E	9D	9C	9B	9A	99	98	
S0CON*#	Serial 0 port control	98H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI	00Н
S0BUF#	Serial 0 data buffer	99H						•			xxxxxxxB
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program status word	D0H	CY	AC	F0	RS1	RS0	OV	F1	Р	00Н
S1DAT#	Serial 1 data	DAH						•			00Н
SP	Stack pointer	81H									07H
S1ADR#	Serial 1 address	DBH			SL	AVE ADDI	RESS ——	<u> </u>		GC	00Н
S1STA#	Serial 1 status	D9H	SC4	SC3	SC2	SC1	SC0	0	0	0	F8H
01017#		Dall	DF	DE	DD	DC	DB	DA	D9	D8	
S1CON*#	Serial 1 control	D8H	CR2	ENS1	STA	STO	SI	AA	CR1	CR0	00000000B
5100N #		Don	8F	8E	8D	8C	8B	8A	89	88	00000000
TCON*	Timer control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	ІТО	00Н
TH1	Timer high 1	8DH									00Н
TH0	Timer high 0	8CH									00H
TL1	Timer low 1	8BH									00H
TL0	Timer low 0	8AH									00H
TMOD	Timer mode	89H	GATE	C/T	M1	MO	GATE	C/T	M1	MO	00H

Table 1. 8XC652/654 Special Function Registers

* SFRs are bit addressable.

SFRs are modified from or added to the 80C51 SFRs.

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CMOS single-chip 8-bit microcontroller

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator, as shown in the Logic Symbol.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

Reset

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on V_{CC} and RST must come up at the same time for a proper start-up.

Idle Mode

In the idle mode, the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

Power-Down Mode

In the power-down mode, the oscillator is stopped and the instruction to invoke

power-down is the last instruction executed. Only the contents of the on-chip RAM are preserved. A hardware reset is the only way to terminate the power-down mode. The control bits for the reduced power modes are in the special function register PCON. Table 2 shows the state of the I/O ports during low current operating modes.

I²C SERIAL COMMUNICATION—SIO1

The l^2C serial port is identical to the l^2C serial port on the 8XC552. The operation of this subsystem is described in detail in the 8XC552 section of this manual.

Note that in both the 8XC652/4 and the 8XC552 the I^2C pins are alternate functions to port pins P1.6 and P1.7. Because of this, P1.6 and P1.7 on these parts do not have a pull-up structure as found on the 80C51. Therefore P1.6 and P1.7 have open drain outputs on the 8XC652/4.

MODE	PROGRAM MEMORY	ALE	PSEN	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Table 2. External Pin Status During Idle and Power-Down Mode

Serial Control Register (S1CON) - See Table 3

S1CON (D8H)

CR2 ENS1 STA STO SI AA CR1 CR0

Bits CR0, CR1 and CR2 determine the serial clock frequency that is generated in the master mode of operation.

Table 3. Serial Clock Rates

			BIT FREG	QUENCY (kHz	z) AT f _{OSC}		
CR2	CR1	CR0	6MHz	12MHz	16MHz	20MHz	f _{OSC} DIVIDED BY
0	0	0	23	47	62.5	78	256
0	0	1	27	54	71	89 ¹	224
0	1	0	31.25	62.5	83.3	104 ¹	192
0	1	1	37	75	100	125 ¹	160
1	0	0	6.25	12.5	17	21	960
1	0	1	50	100	133 ¹	166 ¹	120
1	1	0	100	200 ¹	267 ¹	334 ¹	60
1	1	1	0.25 < 62.5 0 to 255	0.5 < 62.5 0 to 254	0.65 < 55.6 0 to 253	0.81 < 69.4 0 to 253	$96 \times (256 - (reload value Timer 1))$ (Reload value range: $0 - 254$ in mode 2)

NOTES:

1. These frequencies exceed the upper limit of 100kHz of the I²C-bus specification and cannot be used in an I²C-bus application.

ABSOLUTE MAXIMUM RATINGS^{1, 2, 3}

PARAMETER	RATING	UNIT
Storage temperature range	-65 to +150	°C
Voltage on \overline{EA}/V_{PP} to V_{SS}	–0.5 to + 13	V
Voltage on any other pin to V_{SS}	-0.5 to + 6.5	V
Input, output current on any single pin	±5	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1	W

NOTES:

 Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.

2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.

Parameters are valid over operating temperature range unless otherwise specified. All
voltages are with respect to V_{SS} unless otherwise noted.

DEVICE SPECIFICATIONS

	SUPPLY VOLTAGE (V)		FREQU (MI		TEMPERATURE RANGE
TYPE	MIN.	MAX.	MIN.	MAX.	(° C)
S87C654–4	4.5	5.5	3.5	16	0 to +70
S87C654–5	4.5	5.5	3.5	16	-40 to +85
S87C654–7	4.5	5.5	3.5	20	0 to +70
S87C654–8	4.5	5.5	3.5	20	-40 to +85

DC ELECTRICAL CHARACTERISTICS

Vee	=	0V
V SS	-	0.0

			TEST	LIN	IITS	
SYMBOL	PARAMETER	PART TYPE	CONDITIONS	MIN.	MAX.	UNIT
V _{IL}	Input low voltage, except EA, P1.6/SCL, P1.7/SDA	0 to +70°C −40 to +85°C		-0.5 -0.5	0.2V _{CC} -0.1 0.2V _{CC} -0.15	V V
V_{IL1}	Input low voltage to EA	0 to +70°C –40 to +85°C		-0.5 -0.5	$\substack{0.2V_{CC}-0.3\\0.2V_{CC}-0.35}$	V V
V _{IL2}	Input low voltage to P1.6/SCL, P1.7/SDA ¹			-0.5	0.3V _{CC}	V
V _{IH}	Input high voltage, except XTAL1, RST, P1.6/SCL, P1.7/SDA	0 to +70°C –40 to +85°C		0.2V _{CC} +0.9 0.2V _{CC} +1.0	V _{CC} +0.5 V _{CC} +0.5	V V
V _{IH1}	Input high voltage, XTAL1, RST	0 to +70°C –40 to +85°C		0.7V _{CC} 0.7V _{CC} +0.1	V _{CC} +0.5 V _{CC} +0.5	V V
V _{IH2}	Input high voltage, P1.6/SCL, P1.7/SDA ¹			0.7V _{CC}	6.0	V
V _{OL}	Output low voltage, ports 1, 2, 3, except P1.6/SCL, P1.7/SDA		I _{OL} = 1.6mA ^{2, 3}		0.45	V
V _{OL1}	Output low voltage, port 0, ALE, PSEN		I _{OL} = 3.2mA ^{2, 3}		0.45	V
V _{OL2}	Output low voltage, P1.6/SCL, P1.7/SDA		I _{OL} = 3.0mA		0.4	V
V _{OH}	Output high voltage, ports 1, 2, 3	0 to +70°C −40 to +85°C	I _{OH} = –60μΑ I _{OH} = –25μΑ	2.4 0.75V _{CC}		V V
V _{OH1}	Output high voltage; port 0 in external bus mode, ALE, PSEN, RST ⁴	0 to +70°C −40 to +85°C	I _{OH} = -400μA I _{OH} = -150μA	2.4 0.75V _{CC}		V V
IIL	Logical 0 input current, ports 1, 2, 3, 4, except P1.6/SCL, P1.7/SDA	0 to +70°C −40 to +85°C	V _{IN} = 0.45V		-50 -75	μΑ μΑ
I _{TL}	Logical 1-to-0 transition current, ports 1, 2, 3, except P1.6/SCL, P1.7/SDA	0 to +70°C −40 to +85°C	See note 5		-650 -750	μΑ μΑ
I _{L1}	Input leakage current, port 0		$0.45V < V_{\rm I} < V_{\rm CC}$		±10	μA
I_{L2}	Input leakage current, P1.6/SCL, P1.7/SDA		$0V < V_{I} < 6.0V$ $0V < V_{CC} < 6.0V$		±10	μΑ μΑ
ICC	Power supply current: Active mode @ 16MHz ⁷ Idle mode @ 16MHz ⁸ Power down mode ^{9, 10} Power down mode ^{9, 10}	0 to +70°C −40 to +85°C	See note 6 V _{CC} =6.0V		25 6 50 135	mA mA μA μA
R _{RST}	Internal reset pull-down resistor			50	150	kΩ
C _{IO}	Pin capacitance		Freq.=1MHz		10	pF

NOTES: See Next Page.

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NOTES FOR DC ELECTRICAL CHARACTERISTICS:

- The input threshold voltage of P1.6 and P1.7 (SIO1) meets the I²C specification, so an input voltage below 0.3V_{CC} will be recognized as a 1. logic 0 while an input voltage above 0.7V_{CC} will be recognized as a logic 1.
- Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the Vol s of ALE and ports 1 and 3. The noise is due 2. to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. Iol can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
- Under steady state (non-transient) conditions, IoL must be externally limited as follows: Maximum IoL = 10mA per port pin; Maximum 3. IoL = 26mA total for Port 0; Maximum IoL = 15mA total for Ports 1, 2, and 3; Maximum IoL = 71mA total for all output pins. If IoL exceeds the test conditions, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and PSEN to momentarily fall below the 0.9 V_{CC} specification when the
- 4. address bits are stabilizing.
- Pins of ports 1, 2, and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its 5. maximum value when VIN is approximately 2V.
- 6. See Figures 9 through 11 for I_{CC} test conditions.
- The operating supply current is measured with all output pins disconnected; XTAL1 driven with $t_r = t_f = 10ns$; 7.
- VIL = V_{SS} + 0.5V; V_{IH} = V_{CC} -0.5V; XTAL2 not connected; EA = RST = Port 0 = P1.6 = P1.7 = V_{CC}; f_{CLK} = 16MHz. See Figure 9. The idle mode supply current is measured with all output pins disconnected; XTAL1 driven with $t_r = t_r = 10ns$; $V_{IL} = V_{SS} + 0.5V$; 8.
- $V_{IH} = V_{CC} 0.5V$; XTAL2 not connected; Port 0 = P1.6 = P1.7 = V_{CC} ; EA = RST = V_{SS} ; f_{CLK} = 16MHz. See Figure 10. The power-down current is measured with all output pins disconnected; XTAL2 not connected; Port 0 = P1.6 = P1.7 = V_{CC} ; 9 $\overline{EA} = RST = V_{SS}$. See Figure 11.
- $10.2V \le V_{PD} \le V_{CC}$ max.

AC ELECTRICAL CHARACTERISTICS^{1, 2}

			16MHz	CLOCK	VARIABL	E CLOCK	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	UNIT
1/t _{CLCL}	2	Oscillator frequency Speed Versions 87C654 -4, -5			3.5	16	MHz
t _{LHLL}	2	ALE pulse width	85		2t _{CLCL} -40		ns
t _{AVLL}	2	Address valid to ALE low	8		t _{CLCL} -55		ns
t _{LLAX}	2	Address hold after ALE low	28		t _{CLCL} -35		ns
t _{LLIV}	2	ALE low to valid instruction in		150		4t _{CLCL} -100	ns
t _{LLPL}	2	ALE low to PSEN low	23		t _{CLCL} -40		ns
t _{PLPH}	2	PSEN pulse width	143		3t _{CLCL} -45		ns
t _{PLIV}	2	PSEN low to valid instruction in		83		3t _{CLCL} -105	ns
t _{PXIX}	2	Input instruction hold after PSEN	0		0		ns
t _{PXIZ}	2	Input instruction float after PSEN		38		t _{CLCL} -25	ns
t _{AVIV}	2	Address to valid instruction in		208		5t _{CLCL} -105	ns
t _{PLAZ}	2	PSEN low to address float		10		10	ns
Data Memo	ry	•			-		
t _{AVLL}	3, 4	Address valid to ALE low	28		t _{CLCL} -35		ns
t _{RLRH}	3, 4	RD pulse width	275		6t _{CLCL} -100		ns
t _{WLWH}	3, 4	WR pulse width	275		6t _{CLCL} -100		ns
t _{RLDV}	3, 4	RD low to valid data in		148		5t _{CLCL} -165	ns
t _{RHDX}	3, 4	Data hold after RD	0		0		ns
t _{RHDZ}	3, 4	Data float after RD		55		2t _{CLCL} -70	ns
t _{LLDV}	3, 4	ALE low to valid data in		350		8t _{CLCL} –150	ns
t _{AVDV}	3, 4	Address to valid data in		398		9t _{CLCL} -165	ns
t _{LLWL}	3, 4	ALE low to RD or WR low	138	238	3t _{CLCL} -50	3t _{CLCL} +50	ns
t _{AVWL}	3, 4	Address valid to WR low or RD low	120		4t _{CLCL} -130		ns
t _{QVWX}	3, 4	Data valid to WR transition	3		t _{CLCL} -60		ns
t _{DW}	3, 4	Data setup time before WR	288		7t _{CLCL} -150		ns
t _{WHQX}	3, 4	Data hold after WR	13		t _{CLCL} –50		ns
t _{RLAZ}	3, 4	RD low to address float		0		0	ns
t _{WHLH}	3, 4	RD or WR high to ALE high	23	103	t _{CLCL} -40	t _{CLCL} +40	ns
Shift Regist	ter	•		•	-		
t _{XLXL}	5	Serial port clock cycle time ³	0.75		12t _{CLCL}		μs
t _{QVXH}	5	Output data setup to clock rising edge ³	492		10t _{CLCL} -133		ns
t _{XHQX}	5	Output data hold after clock rising edge ³	80		2t _{CLCL} -117		ns
t _{XHDX}	5	Input data hold after clock rising edge ³	0		0		ns
t _{XHDV}	5	Clock rising edge to input data valid ³		492	1	10t _{CLCL} -133	ns
External Cl	ock	•	•		•	-	
t _{CHCX}	6	High time ³	20		20	t _{CLCL -} t _{LOW}	ns
t _{CLCX}	6	Low time ³	20		20	t _{CLCL} - t _{HIGH}	ns
t _{CLCH}	6	Rise time ³		20		20	ns
tCHCL	6	Fall time ³		20		20	ns

NOTES:

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
 These values are characterized but not 100% production tested.

AC ELECTRICAL CHARACTERISTICS^{1, 2}

			20MHz	CLOCK	VARIABL	E CLOCK	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	МАХ	UNIT
1/t _{CLCL}	2	Oscillator frequency: Speed Versions 87C654 -7, -8			3.5	20	MHz
t _{LHLL}	2	ALE pulse width	60		2t _{CLCL} -40		ns
t _{AVLL}	2	Address valid to ALE low	25		t _{CLCL} -25		ns
t _{LLAX}	2	Address hold after ALE low	25		t _{CLCL} -25		ns
t _{LLIV}	2	ALE low to valid instruction in		135		4t _{CLCL} -65	ns
t _{LLPL}	2	ALE low to PSEN low	25		t _{CLCL} -25		ns
t _{PLPH}	2	PSEN pulse width	105		3t _{CLCL} -45		ns
t _{PLIV}	2	PSEN low to valid instruction in		90		3t _{CLCL} -60	ns
t _{PXIX}	2	Input instruction hold after PSEN	0		0		ns
t _{PXIZ}	2	Input instruction float after PSEN		25		t _{CLCL} -25	ns
t _{AVIV}	2	Address to valid instruction in		170		5t _{CLCL} -80	ns
t _{PLAZ}	2	PSEN low to address float		10		10	ns
Data Memo	ry	-			-		
t _{AVLL}	3, 4	Address valid to ALE low	25		t _{CLCL} -25		ns
t _{RLRH}	3, 4	RD pulse width	200		6t _{CLCL} -100		ns
t _{WLWH}	3, 4	WR pulse width	200		6t _{CLCL} -100		ns
t _{RLDV}	3, 4	RD low to valid data in		160		5t _{CLCL} -90	ns
t _{RHDX}	3, 4	Data hold after RD	0		0		ns
t _{RHDZ}	3, 4	Data float after RD		72		2t _{CLCL} -28	ns
t _{LLDV}	3, 4	ALE low to valid data in		250		8t _{CLCL} -150	ns
t _{AVDV}	3, 4	Address to valid data in		285		9t _{CLCL} -165	ns
t _{LLWL}	3, 4	ALE low to RD or WR low	100	200	3t _{CLCL} -50	3t _{CLCL} +50	ns
t _{AVWL}	3, 4	Address valid to WR low or RD low	125		4t _{CLCL} -75		ns
t _{QVWX}	3, 4	Data valid to WR transition	20		t _{CLCL} -30		ns
t _{DW}	3, 4	Data setup time before WR	220		7t _{CLCL} -130		ns
t _{WHQX}	3, 4	Data hold after WR	25		t _{CLCL} -25		ns
t _{RLAZ}	3, 4	RD low to address float		0		0	ns
t _{WHLH}	3, 4	RD or WR high to ALE high	25	75	t _{CLCL} -25	t _{CLCL} +25	ns
Shift Regis	ter	-			-	-	
t _{XLXL}	5	Serial port clock cycle time ³	0.6		12t _{CLCL}		μs
t _{QVXH}	5	Output data setup to clock rising edge ³	367		10t _{CLCL} -133		ns
t _{XHQX}	5	Output data hold after clock rising edge ³	40		2t _{CLCL} -60		ns
t _{XHDX}	5	Input data hold after clock rising edge ³	0		0		ns
t _{XHDV}	5	Clock rising edge to input data valid ³		367		10t _{CLCL} -133	ns
External Cl	ock		-	-	-	-	-
t _{CHCX}	6	High time ³	17		17	t _{CLCL} – t _{LOW}	ns
t _{CLCX}	6	Low time ³	17		17	t _{CLCL} – t _{HIGH}	ns
tCLCH	6	Rise time ³		20		20	ns
tCHCL	6	Fall time ³		20		20	ns

14

NOTES:

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
 These values are characterized but not 100% production tested.

Philips Semiconductors

CMOS single-chip 8-bit microcontroller

87C654

AC ELECTRICAL CHARACTERISTICS – I²C INTERFACE

SYMBOL	PARAMETER	INPUT	OUTPUT
SCL TIMI	NG CHARACTERISTICS		
t _{HD} ; STA	START condition hold time	\geq 14 t _{CLCL}	> 4.0µs ¹
t _{LOW}	SCL LOW time	≥ 16 t _{CLCL}	> 4.7µs ¹
t _{HIGH}	SCL HIGH time	≥ 14 t _{CLCL}	> 4.0µs ¹
t _{RC}	SCL rise time	≤ 1μs	_ 2
t _{FC}	SCL fall time	≤ 0.3µs	< 0.3μs ³
SDA TIMI	NG CHARACTERISTICS		
t _{SU} ; DAT1	Data set-up time	≥ 250ns	> 20 t _{CLCL} – t _{RD}
t _{SU} ; DAT2	SDA set-up time (before rep. START cond.)	≥ 250ns	> 1µs¹
t _{SU} ; DAT3	SDA set-up time (before STOP cond.)	≥ 250ns	> 8 t _{CLCL}
t _{HD} ; DAT	Data hold time	≥ 0ns	> 8 t _{CLCL} – t _{FC}
t _{SU} ; STA	Repeated START set-up time	\geq 14 t _{CLCL}	> 4.7µs ¹
t _{SU} ; STO	STOP condition set-up time	\geq 14 t _{CLCL}	> 4.0µs ¹
t _{BUF}	Bus free time	\geq 14 t _{CLCL}	> 4.7µs ¹
t _{RD}	SDA rise time	≤ 1μs	_ 2
t _{FD}	SDA fall time	≤ 0.3μs	< 0.3μs ³

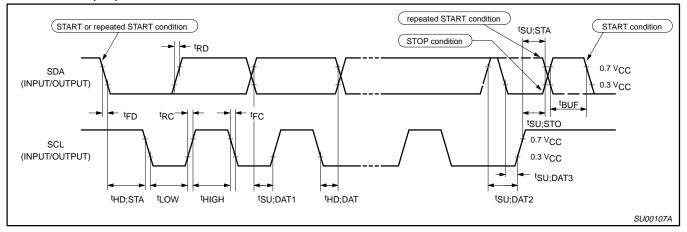
NOTES:

1. At 100 kbit/s. At other bit rates this value is inversely proportional to the bit-rate of 100 kbit/s.

2. Determined by the external bus-line capacitance and the external bus-line pull-resistor, this must be $< 1\mu$ s.

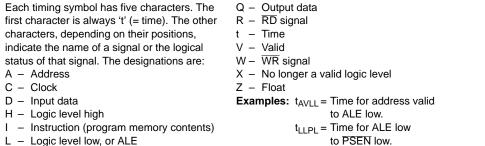
 Spikes on the SDA and SCL lines with a duration of less than 3 t_{CLCL} will be filtered out. Maximum capacitance on bus-lines SDA and SCL = 400pF.

 t_{CLCL} = 1/f_{OSC} = one oscillator clock period at pin XTAL1. For 62ns < t_{CLCL} < 285ns (16MHz) > f_{OSC} > 3.5MHz) the SI01 interface meets the I²C-bus specification for bit-rates up to 100 kbit/s.

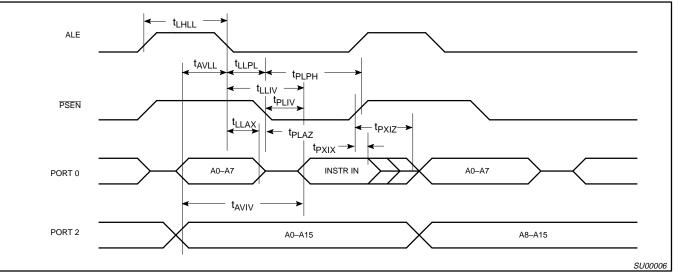


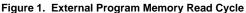
TIMING SIO1 (I²C) INTERFACE

EXPLANATION OF THE AC SYMBOLS



P - PSEN





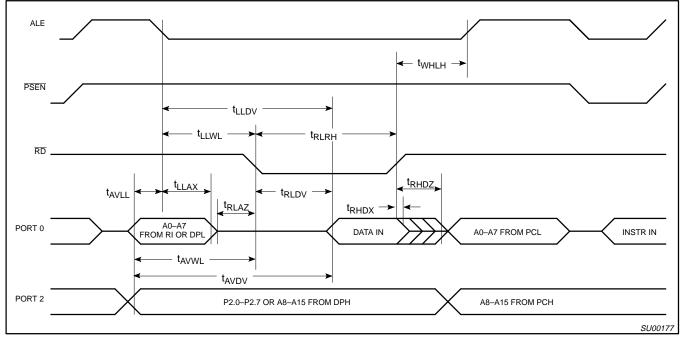


Figure 2. External Data Memory Read Cycle

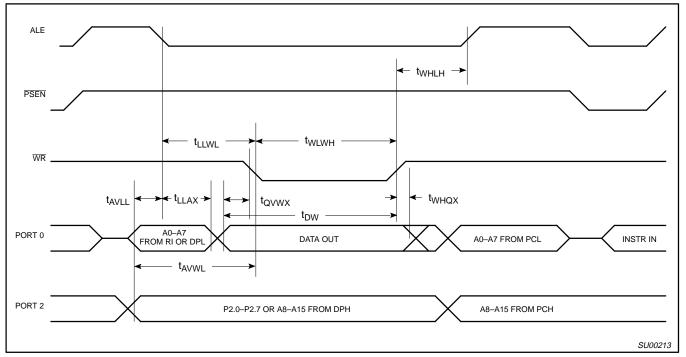


Figure 3. External Data Memory Write Cycle

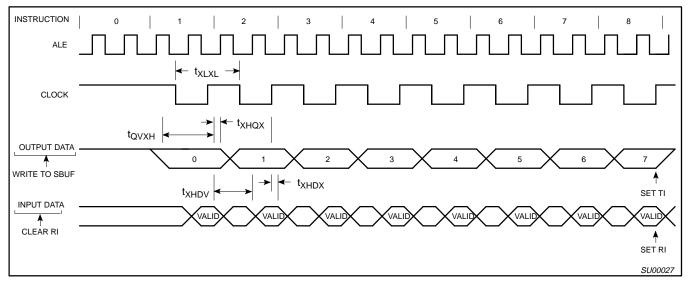


Figure 4. Shift Register Mode Timing

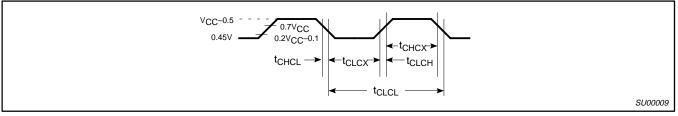
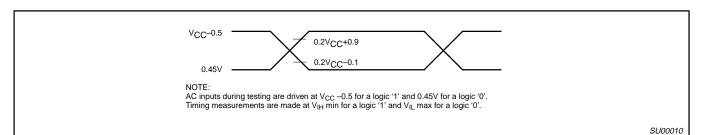


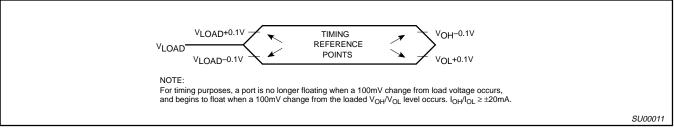
Figure 5. External Clock Drive



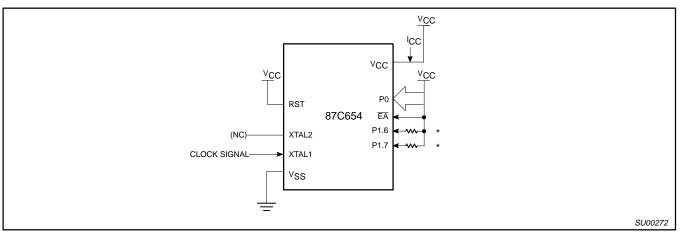
Product specification

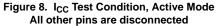












NOTE:

Ports 1.6 and 1.7 should be connected to V_{CC} through resistors of sufficiently high value such that the sink current into these pins does not exceed the I_{OL1} specification.

87C654

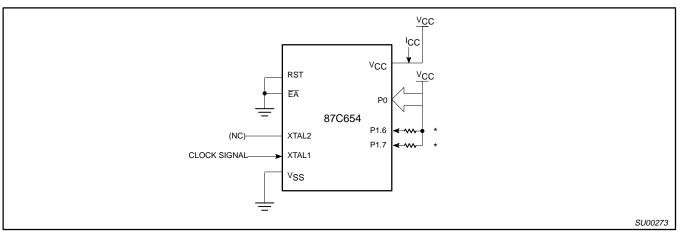
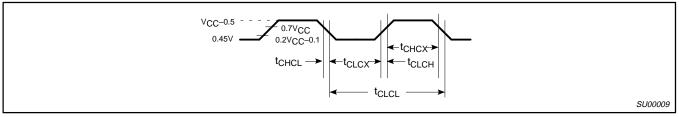
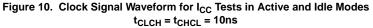


Figure 9. I_{CC} Test Condition, Idle Mode All other pins are disconnected





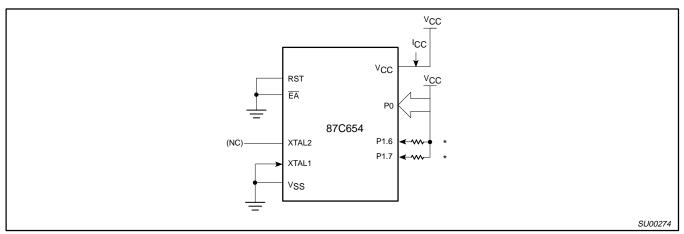


Figure 11. I_{CC} Test Condition, Power Down Mode All other pins are disconnected. V_{CC} = 2V to 5.5V

NOTE:

Ports 1.6 and 1.7 should be connected to V_{CC} through resistors of sufficiently high value such that the sink current into these pins does not exceed the I_{OL1} specification.

87C654

CMOS single-chip 8-bit microcontroller

EPROM CHARACTERISTICS

The 87C654 is programmed by using a modified Quick-Pulse Programming[™] algorithm. It differs from older methods in the value used for V_{PP} (programming supply voltage) and in the width and number of the ALE/PROG pulses.

The 87C654 contains two signature bytes that can be read and used by an EPROM programming system to identify the device. The signature bytes identify the device as an 87C654 manufactured by Philips Components.

Table 4 shows the logic levels for reading the signature byte, and for programming the program memory, the encryption table, and the lock bits. The circuit configuration and waveforms for quick-pulse programming are shown in Figures 12 and 13. Figure 14 shows the circuit configuration for normal program memory verification.

Quick-Pulse Programming

The setup for microcontroller quick-pulse programming is shown in Figure 12. Note that the 87C654 is running with a 4 to 6MHz oscillator. The reason the oscillator needs to be running is that the device is executing internal address and program data transfers.

The address of the EPROM location to be programmed is applied to ports 1 and 2, as shown in Figure 12. The code byte to be programmed into that location is applied to port 0. RST, <u>PSEN</u> and pins of ports 2 and 3 specified in Table 4 are held at the 'Program Code Data' levels indicated in Table 4. The ALE/PROG is pulsed low 25 times as shown in Figure 13. To program the encryption table, repeat the 25 pulse programming sequence for addresses 0 through 1FH, using the 'Pgm Encryption Table' levels. Do not forget that after the encryption table is programmed, verification cycles will produce only encrypted data.

To program the lock bits, repeat the 25 pulse programming sequence using the 'Pgm Lock Bit' levels. After one lock bit is programmed, further programming of the code memory and encryption table is disabled. However, the other lock bit can still be programmed.

Note that the $\overline{EA/V_{PP}}$ pin must not be allowed to go above the maximum specified V_{PP} level for any amount of time. Even a narrow glitch above that voltage can cause permanent damage to the device. The V_{PP} source should be well regulated and free of glitches and overshoot.

Program Verification

If lock bit 2 has not been programmed, the on-chip program memory can be read out for program verification. The address of the program memory locations to be read is applied to ports 1 and 2 as shown in Figure 14. The other pins are held at the 'Verify Code Data' levels indicated in Table 4. The contents of the address location will be emitted on port 0. External pull-ups are required on port 0 for this operation.

If the encryption table has been programmed, the data presented at port 0 will be the exclusive NOR of the program byte with one of the encryption bytes. The user will have to know the encryption table contents in order to correctly decode the verification data. The encryption table itself cannot be read out.

Reading the Signature Bytes

The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 need to be pulled to a logic low. The values are:

- (030H) = 15H indicates manufactured by Philips
- (031H) = 99H indicates 87C654

Program/Verify Algorithms

Any algorithm in agreement with the conditions listed in Table 4, and which satisfies the timing specifications, is suitable.

Erasure Characteristics

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room level fluorescent lighting) could cause inadvertent erasure. For this and secondary effects, it is recommended that an opaque label be placed over the window. For elevated temperature or environments where solvents are being used, apply Kapton tape Fluorglas part number 2345–5, or equivalent.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 angstroms) to an integrated dose of at least 15W-sec/cm². Exposing the EPROM to an ultraviolet lamp of 12,000 μ W/cm² rating for 20 to 39 minutes, at a distance of about 1 inch, should be sufficient. Erasure leaves the array in an all 1s state.

PSEN 0	ALE/PROG	EA/V _{PP}	P2.7	P2.6	P3.7	P3.6
0	1					
		1	0	0	0	0
0	0*	V _{PP}	1	0	1	1
0	1	1	0	0	1	1
0	0*	V _{PP}	1	0	1	0
0	0*	V _{PP}	1	1	1	1
0	0*	V _{PP}	1	1	0	0
	0	0 0*	0 0* V _{PP}	0 0* V _{PP} 1	0 0* V _{PP} 1 1	0 0* V _{PP} 1 1 1

Table 4. EPROM Programming Modes

NOTES:

1. 0' = Valid low for that pin, 1' = valid high for that pin.

2. $V_{PP} = 12.75V \pm 0.25V.$

3. $V_{CC} = 5V \pm 10\%$ during programming and verification.

ALE/PROG receives 25 programming pulses while V_{PP} is held at 12.75V. Each programming pulse is low for 100μs (±10μs) and high for a minimum of 10μs.

[™]Trademark phrase of Intel Corporation.

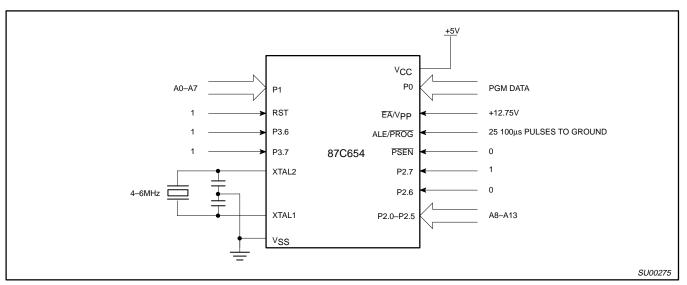


Figure 12. Programming Configuration

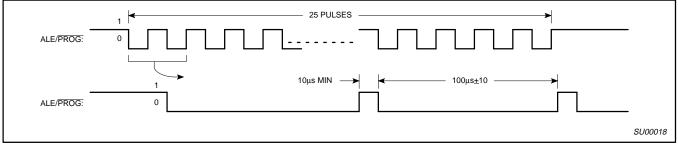


Figure 13. PROG Waveform

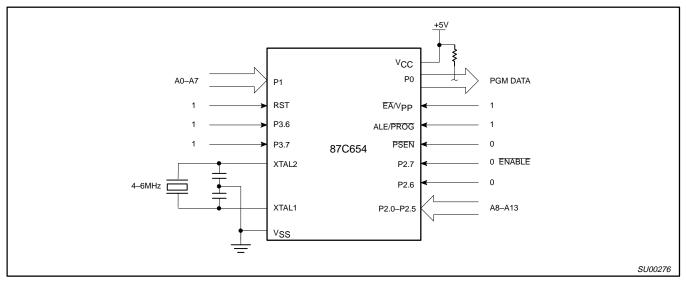


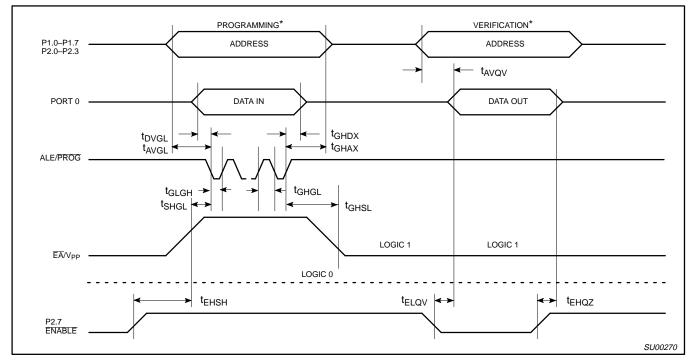
Figure 14. Program Verification

87C654

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

 T_{amb} = 21°C to +27°C, V_{CC} = 5V±10%, V_{SS} = 0V (See Figure 15)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V _{PP}	Programming supply voltage	12.5	13.0	V
I _{PP}	Programming supply current		50	mA
1/t _{CLCL}	Oscillator frequency	4	6	MHz
t _{AVGL}	Address setup to PROG low	48t _{CLCL}		
t _{GHAX}	Address hold after PROG	48t _{CLCL}		
t _{DVGL}	Data setup to PROG low	48t _{CLCL}		
t _{GHDX}	Data hold after PROG	48t _{CLCL}		
t _{EHSH}	P2.7 (ENABLE) high to V _{PP}	48t _{CLCL}		
t _{SHGL}	V _{PP} setup to PROG low	10		μs
t _{GHSL}	V _{PP} hold after PROG	10		μs
t _{GLGH}	PROG width	90	110	μs
t _{AVQV}	Address to data valid		48t _{CLCL}	
t _{ELQZ}	ENABLE low to data valid		48t _{CLCL}	
t _{EHQZ}	Data float after ENABLE	0	48t _{CLCL}	
t _{GHGL}	PROG high to PROG low	10		μs

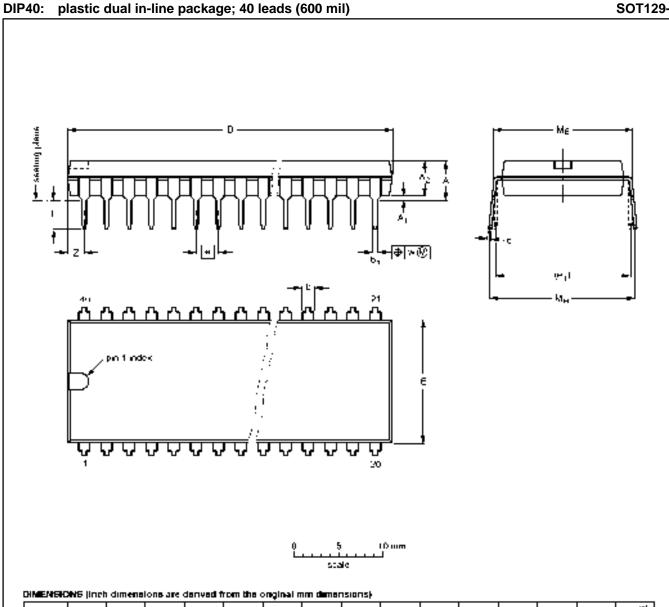


FOR PROGRAMMING VERIFICATION SEE FIGURE 12. FOR VERIFICATION CONDITIONS SEE FIGURE 14.

Figure 15. EPROM Programming and Verification



Purchase of Philips I^2C components conveys a license under the Philips' I^2C patent to use the components in the I^2C system provided the system conforms to the I^2C specifications defined by Philips. This specification can be ordered using the code 9398 393 40011.



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Note

1. Plastic or metal protosions of 0.25 mm maximum per side are not included.

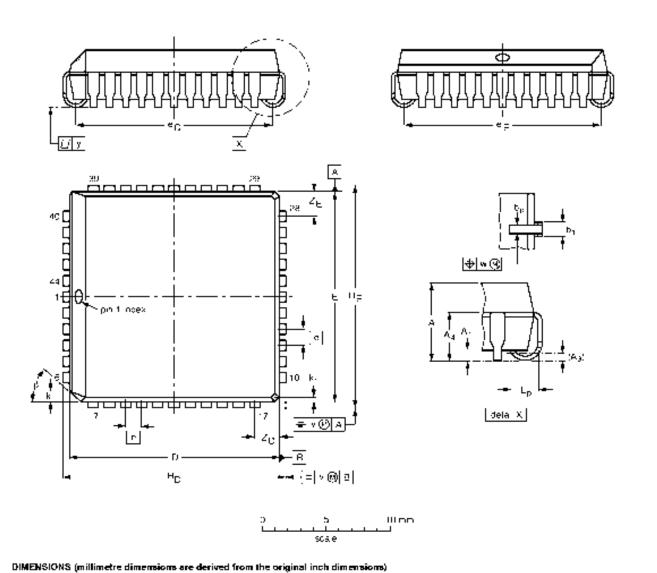
OUTLINE		REFER	IENCIES	BUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	IBBOE DATE
SOT179-1	05 (GOR	MD-015AJ		€∃⊕	92 14 95-01-14

Product specification 87C654

1996 Aug 16

CMOS single-chip 8-bit microcontroller





UNIT	A .	A1 min.	Α3	A4 max.	Ьр	Þ,	D ⁽¹⁾	$\mathbf{E}^{(1)}$	0	*D	θE	но	HE	ĸ	k ₁ max.	Lp	4	w	У	Z D ⁽¹⁾ max.	Ζ _Ε ⁽¹⁾ max.	в
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Note

1. Plastic or metal brollrusions of 0.01 inches maximum per side are not included

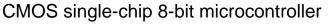
OUTLINE		REFER	IENCES	EUROPEAN	ISSUE DATE	
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SOT187-2	12E10	MC-047AC		¢ [92-11-17 95-02-25	

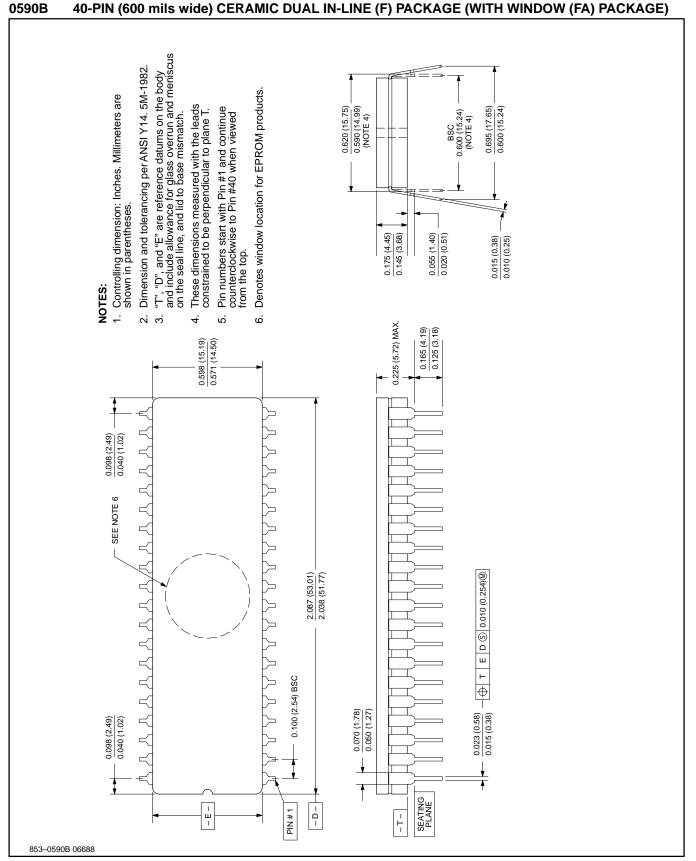
QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm SOT307-2 ннннн 1 $\overline{U}(\mathbf{y})$ А ****8888888888888***** 34 ZF <u>ава</u>щава ি a н_ь Ε Ŧ @ • **@** $\mathbf{b}_{\boldsymbol{\rho}}$ pin Lindex Т 12 44 delai X $= \sim \odot \land$ whi ল D ≡িথিচ нп 25 Saim stale DEMENSIONS (mm are the original dimensions) z _Em A max $z_0^{(n)}$ DIII E UNIT ۵ A Ag Ag Þ_E c 4 нь ΗE L ц ¥ w γ • • 160 () 1() 0.25 10.1 10.1 12.9 12.9 0.95 0.05 1.2 12 10° 0.25 2 10 08 01 0.25 1.3 0.15 0.13 0.05 166 0.20 0.14 0.55 0.75 09 a° \$\$ 88 12.5 12.0 ч **9** Note 1. Plasbo or metal protrusions of 0.20 mm maximum per side are not included REFERENCES OUTLINE EUROPEAN ISSUE DATE VERSION PROJECTION IEC JEDEC EIAJ 42-11-17 501207.2

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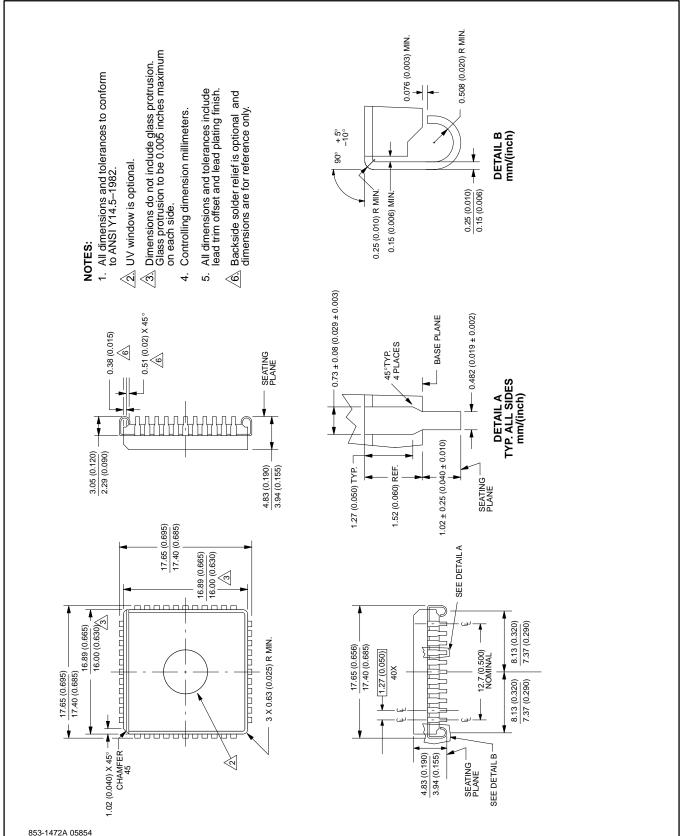
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1472A 44-PIN CERQUAD J-BEND (K) PACKAGE

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Data Sheet Identification	Product Status	Definition								
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